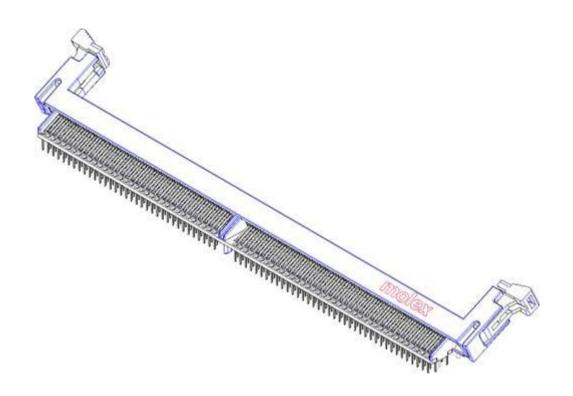


SIGNAL INTEGRITY TEST SUMMARY DDR4 DIMM 0.85MM PITCH 25 DEGREES CONNECTOR



1.0 SCOPE

This test summary covers the signal integrity performance of DDR4 DIMM 0.85mm Pitch 25 Degrees through-hole connector. The measurement was conducted using Molex DDR4 Angled 25 Degrees test fixture. Most of the test fixture effect was removed using AFR in PLTS.

2.0 PRODUCT DESCRIPTION

2.1 PRODUCT NAME AND PART NUMBER

DDR4 DIMM 0.85mm Pitch 25 Degrees through-hole connector, Part # 151080-0101.

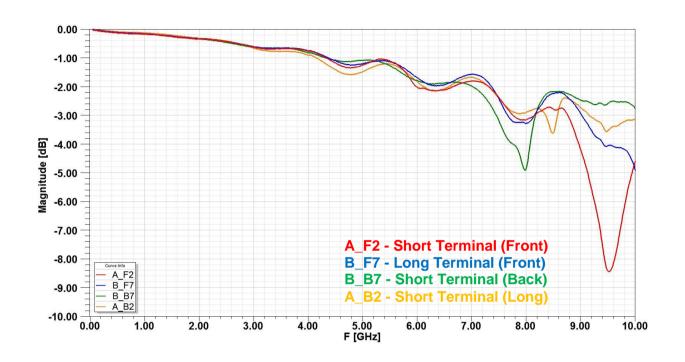
REVISION:	ECN INFORMATION: EC No: \$2015-1365 DATE: 2015/05/22	DDR 25	I Integrity Test Summary 4 DIMM 0.85MM PITCH Deg T/H CONNECTOR DLEX CONFIDENTIAL	•	1 of 11
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	APPRO\	/ED BY:
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2	2015/05/22



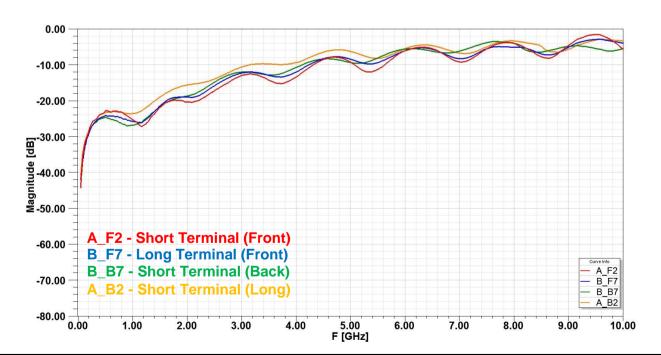
3.0 PERFORMANCE

Frequency Domain

Insertion Loss



Return Loss



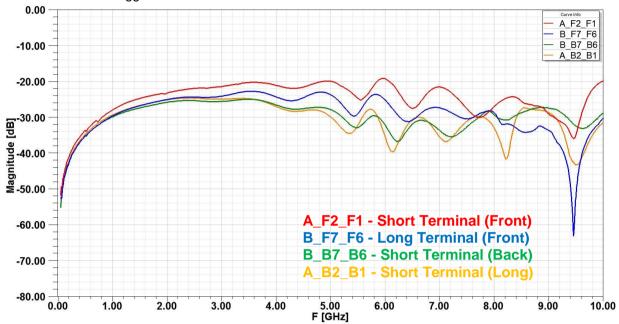
B	ECN INFORMATION: EC No: \$2015-1365 DATE: 2015/05/22	Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL		,	2 of 11
DOCUMENT NUMBER:		CREATED / REVISED BY:	CHECKED BY:	CHECKED BY: APPROVED BY	
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2	2015/05/22



Frequency Domain (continued)

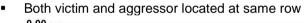
Near End Cross-Talk (Same Side)

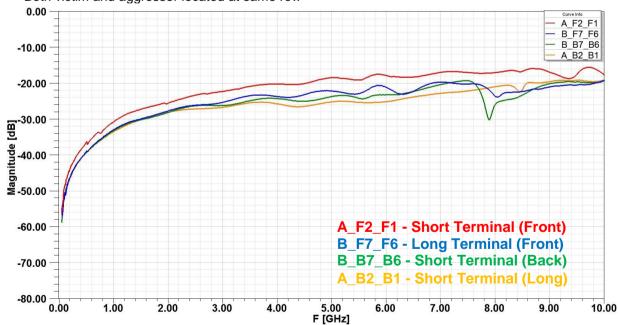
- 1:1 S/G ratio
- Both victim and aggressor located at same row



Far End Cross-Talk (Same Side)

1:1 S/G ratio





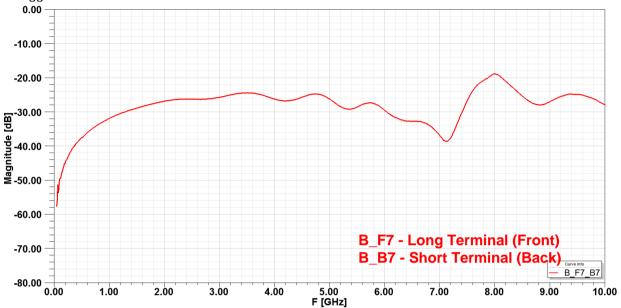
REVISION:	ECN INFORMATION: EC No: \$2015-1365 DATE: 2015/05/22	TITLE: Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL		•	3 of 11
DOCUMEN'	T NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPRO\	<u>/ED BY:</u>
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2	2015/05/22



Frequency Domain (continued)

Near End Cross-Talk (Opposite Side)

- 1:1 S/G ratio
- Victim locates at inner row from front side
- Aggressor locates at inner row from back side



Far End Cross-Talk (Opposite Side)

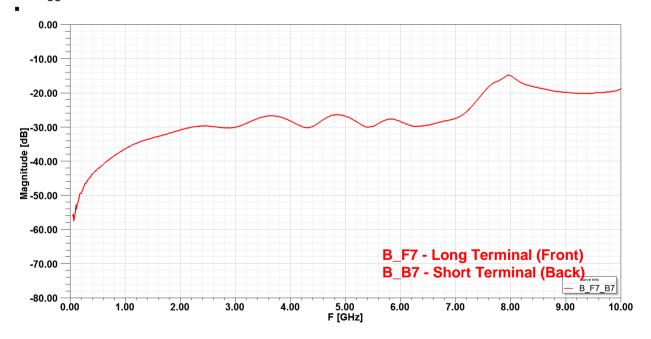
ECN INFORMATION:

TITLE:

1:1 S/G ratio

REVISION:

- Victim locates at inner row from front side
- Aggressor locates at inner row from back side.



В	EC No: \$2015-1365 DATE: 2015/05/22	DDR 25	14 DIMM 0.85MM PITCH Deg T/H CONNECTOR DLEX CONFIDENTIAL		4 of 11
<u>DOCUMEN</u>	T NUMBER:	CREATED / REVISED BY:	CHECKED BY:	<u>APPROV</u>	<u>ED BY:</u>
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2	2015/05/22

Signal Integrity Test Summary

TEMPLATE FILENAME: SPM[SIZE_A](V.1).DOC

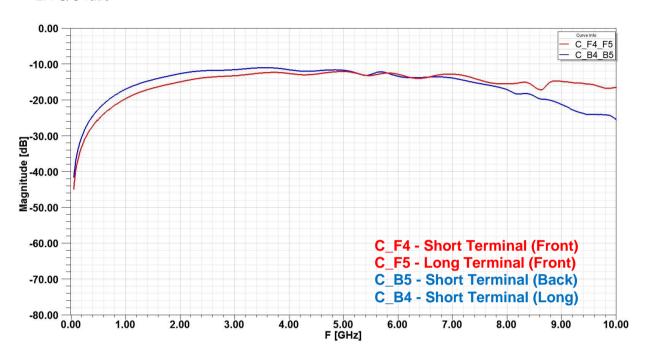
SHEET No.



Frequency Domain (continued)

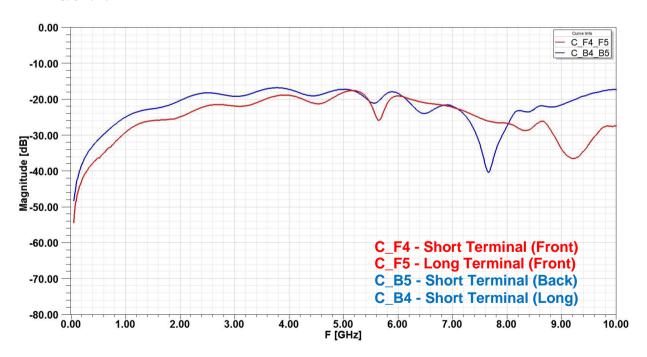
Near End Cross-Talk (Same Side)

2:1 S/G ratio



Far End Cross-Talk (Same Side)

2:1 S/G ratio



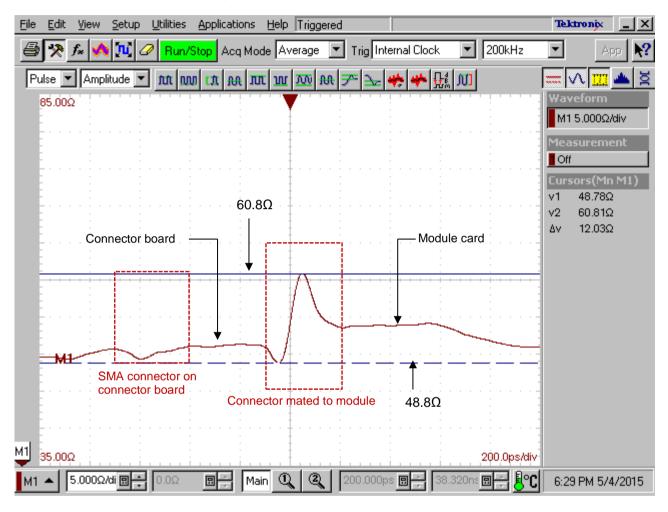
B	EC No: \$2015-1365 DATE: 2015/05/22 IT NUMBER:	25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL CREATED / REVISED BY: CHECKED BY: APPRO		APPROV	5 of 11



Time Domain

TDR Impedance

- A_F2 Short terminal (Front)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint



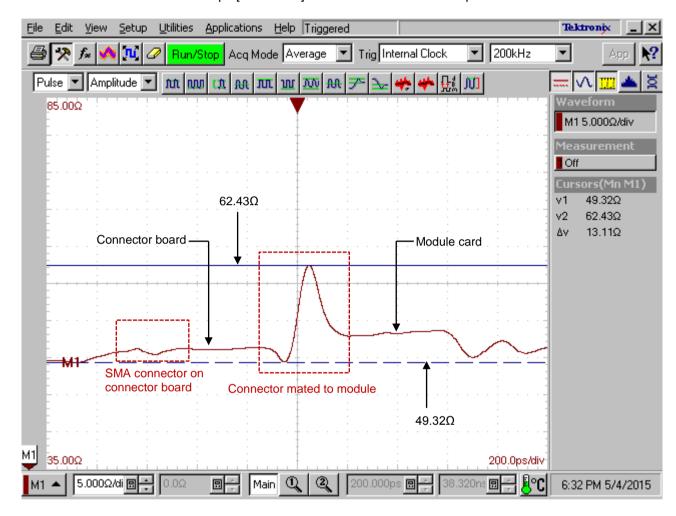
REVISION:	ECN INFORMATION: EC No: \$2015-1365 DATE: 2015/05/22	Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL		SHEET No. 6 of 11	
DOCUMENT NUMBER: TS-151080-0001		CREATED / REVISED BY: WHFOO 2015/05/22	CHECKED BY: CMWONG 2015/05/22	APPRO\	



Time Domain (continued)

TDR Impedance

- B_F7 Long terminal (Front)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint



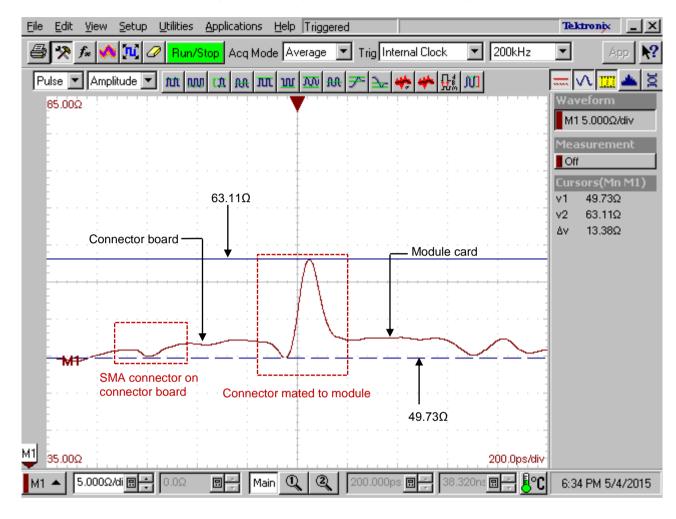
REVISION:	ECN INFORMATION:	Signal Integrity Test Summary		SHEET No.	
Ь	EC No: S2015-1365	DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR			7 04 11
В	DATE: 2015/05/22	MOLEX CONFIDENTIAL			7 of 11
<u>DOCUMEN</u>	T NUMBER:	CREATED / REVISED BY:	CHECKED BY:	<u>APPRO\</u>	/ED BY:
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2	2015/05/22



Time Domain (continued)

TDR Impedance

- B_B7 Short terminal (Back)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint



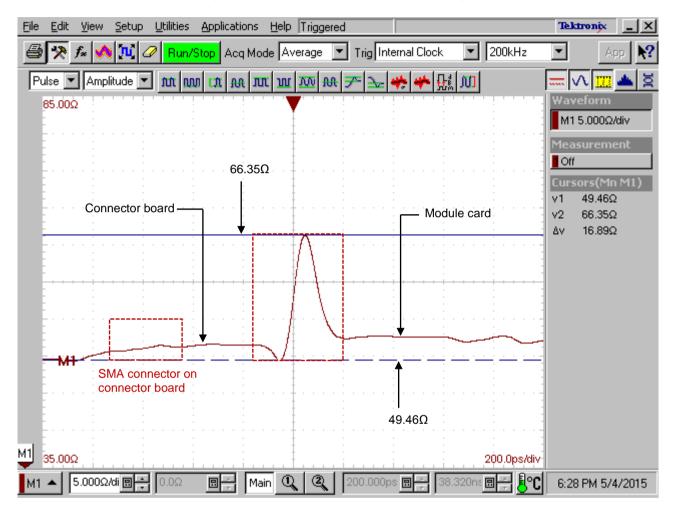
REVISION:	ECN INFORMATION:	Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR		SHEET No.	
В	EC No: S2015-1365			8 of 11	
	DATE: 2015/05/22	MOLEX CONFIDENTIAL			00111
DOCUMEN:	T NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPRO\	/ED BY:
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2	2015/05/22



Time Domain (continued)

TDR Impedance (A_B2)

- A_B2 Long terminal (Back)
- Referenced rise-time of 100ps [10%~90%] launched at connector footprint



REVISION:	ECN INFORMATION:	TITLE: Signal Integrity Test Summary		SHEET No.	
D	EC No: S2015-1365		DDR4 DIMM 0.85MM PITCH		0 -4 11
В	DATE: 2015/05/22	25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL			9 of 11
DOCUMEN	T NUMBER:	CREATED / REVISED BY:	CHECKED BY:	APPRO\	/ED BY:
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2	2015/05/22



4.0TEST FIXTURES



Molex DDR4 Test Fixture Board Information

Material: TU-872-SLK Thickness: 1.4mm

High Speed Traces: High-Speed Signals on Top Layer (referenced to Layer 2) and Bottom Layer

(referenced to Layer 3)

0.09398mm dielectric thickness between Top Layer & Layer 2; Layer 3 & Bottom

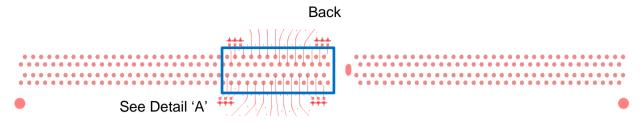
∟ayer

50.8mm single-ended length (both main and module board)

REVISION:	ECN INFORMATION: EC No: \$2015-1365 DATE: 2015/05/22	DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL		,	10 of 11
DOCUMEN'	T NUMBER:	CREATED / REVISED BY:	CHECKED BY:	CKED BY: APPROVED BY:	
TS-151080-0001		WHFOO 2015/05/22	CMWONG 2015/05/22	WTCHUA 2015/05/22	



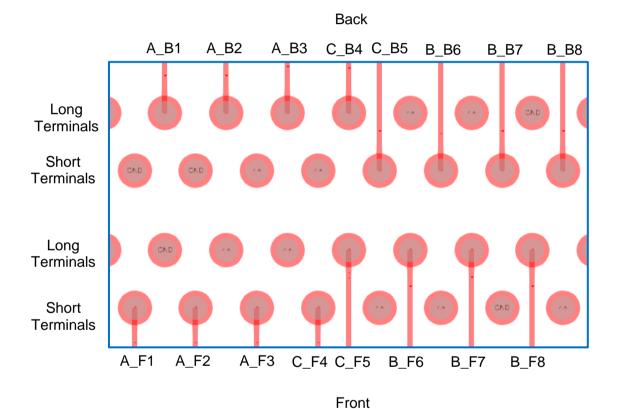
Mainboard Footprint Detail



Front

Detail 'A'

TS-151080-0001



REVISION:	ECN INFORMATION: EC No: \$2015-1365	Signal Integrity Test Summary DDR4 DIMM 0.85MM PITCH 25 Deg T/H CONNECTOR MOLEX CONFIDENTIAL		SHEET No.
В	DATE: 2015/05/22			
DOCUMENT NUMBER:		CREATED / REVISED BY: CHECKED BY: APPROVED B		/ED BY:

WHFOO 2015/05/22

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CMWONG 2015/05/22

WTCHUA 2015/05/22